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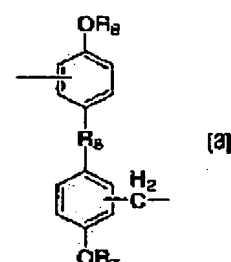
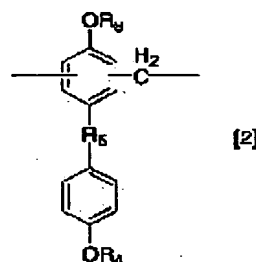
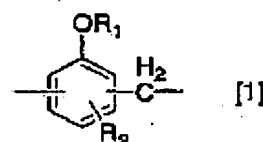
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(54) PHOTOCURABLE AND THERMOSETTING RESIN COMPOSITION

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a photosensitive resin composition capable of developing in an alkaline aqueous solution, processing at a low temperature and giving an excellent heat-resistant resin layer, and a phenol novolak useful as a curing agent for such resin composition.

SOLUTION: The invention discloses a phenol novolak comprising a structural unit represented by general formula [1] and having an organic group consisting of a cis-diene structure as a part of R1 and 3-30 of average degree of polymerization; a phenol novolak which is represented by general formulas [2] and [3], one or both of R3 and R4 and one or both of R6 and R7 are an organic group having a cis-diene structure and average degree of polymerization is 2-25; and a photocurable and thermosetting resin composition containing (a) a polyfunctional epoxy resin, (b) the above-mentioned phenol novolak and (c) an oxygen sensitizer.



LEGAL STATUS

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